

Expander

Reinraumtechnik Lanz's ideal semi-automatic tool for expanding already processed die for easy and accurate pick and placement as well as LED etching process. The diced wafers are uniformly expanded to produce the required die interval which assists the pattern recognition system.

Description

This process is started by inserting the inner hoop over the chuck and outer hoop into the recessed area on the cover.

The tape holding the diced wafers is then placed over the heatable chuck. A clamping ring is also placed around the chuck. After the manual procedure has been carried out, both buttons located on the side of the expander are pushed simultaneously and held down until the expansion process is completed.

The semi-automatic procedure is carried out pneumatically. The chuck moves upward to the set position and the cover (cylinder) is moved down over the chuck where the outer hoop is clamped into the inner hoop fastening the tape. The cutter then cuts off the excess tape.

The expander can also be used manually.



Customized table with expander

Features and Benefits

- Customized to be used with all types of clamping ring systems
- Various hoop sizes to accommodate wafers up to 150mm
- Expansion kerf set according to PRS requirements
- Heated chuck (hotplate) for easier expansion – thermostatically controlled
- Adjustable expansion
- Adjustable, fast, safe and accurate tape cutting
- Customized table sizes available
- Two-hand operation avoids injury to hands
- Optical warning signal for manual mode
- No physical contact to wafer surface avoids damage
- 12 months warranty

For more details, please contact Reinraumtechnik Lanz – Germany at info@rrt-lanz.com

Subject to change without prior notice.



Close-up View of Expander

Facility Requirements

Voltage: 400V, 3 Ph + N + PE, 50 Hz *
Pressure: 6 bar 8mm Ø

* other voltages available

Dimensions

w x d x h: 1500 x 650 x 1650 mm (picture – customized table with Expander)

Option

- Variable expansion speed